WHAT IS CLAIMED IS:

1. A chip device comprising:

a. a die; and

b. a leadframe including a die attach cavity, the die attach cavity having substantially the same thickness as the die;

c. wherein the die is positioned within the die attach cavity and is attached therein.

2. The chip device of claim 1 further comprising a plurality of dimples defined around the periphery of the leadframe that receive solder balls.

3. The chip device of claim 1 wherein the leadframe consists of a copper based alloy.

4. The chip device of claim 3 wherein the leadframe includes a solderable coating.

5. The chip device of claim 1 wherein the die is a bumped die.

6. A chip device comprising:

a. a bumped die;

b. a leadframe including a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die; and

c. a plurality of solder balls placed within the dimples;

wherein the die is positioned within the cavity and is attached therein.

7. The chip device of claim 6 wherein the leadframe consists of a copper based alloy.

8. The chip device of claim 7 wherein the leadframe includes a solderable coating.

9. A method of making a chip device, the method comprising:

providing a die;

providing a leadframe including a die attach cavity and a plurality of dimples defined around a periphery of the leadframe, the die attach cavity having substantially the same thickness as the die;

placing solder balls into the dimples; and

flipping the die into the die attach cavity and attaching it therein.

10. The method of claim 9 wherein the die provided is a bumped die.